

JP 5-105739

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 DN 119:162095
 TI Bisphenol-type **epoxy resin** compositions for sealing
 semiconductor devices
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 SO Jpn. Kokai Tokkyo Koho, 7 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC ICM C08G059-18
 ICS C08G059-62; C08K003-36; C08L063-00; H01L023-29; H01L023-31
 CC 38-3 (Plastics Fabrication and Uses)
 Section cross-reference(s): 76

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|---|------|----------|-----------------|----------|
| PI | JP 05105739 | A2 | 19930427 | JP 1991-296445 | 19911016 |
| AB | Solder heat-resistant title compns. with low stress contain 100 parts epoxy resins contg. .gtoreq.30% biphenyl-type epoxy resins , 300-1000 parts silica filler, 1-30 parts <u>oils (R1)(SiR2R3O)nSiR4 (R1 = epoxy, amino, OH, OH-contg. group, SH; R2-4 =</u> <u>Me, Ph; n = no. to av. mol. wt. 1000-30,000), and 20-100 parts hardeners.</u> <u>Thus, a mixt. of YX 4000 100, tetraphenolethane 50, globular powd. silica</u> <u>500, crushed powd. silica 200, an epoxy-terminated silicone oil 5,</u> <u>.gamma.-glycidoxypropyltrimethoxysilane 4, Ph3P 1, carbon black 3, and a</u> <u>wax 3 parts was kneaded at 110.degree. for 4 min, crushed, molded onto an</u> <u>integrated circuit, and postcured at 85.degree. and 85% humidity for 72 h</u> <u>to give a test piece, which was impregnated with solder bath at</u> <u>260.degree. for 10 s to show no cracks.</u> | | | | |
| ST | semiconductor device sealant epoxy resin ; solder heat crack resistance sealant; biphenyl epoxy resin siloxane sealant; silica filler epoxy resin sealant | | | | |
| IT | Potting compositions (biphenyl-type epoxy resins contg. siloxanes, with solder heat resistance, for semiconductor devices) | | | | |
| IT | Heat-resistant materials (bisphenol-type epoxy resin -siloxanes, sealants, for semiconductor devices) | | | | |
| IT | Phenolic resins, uses RL: MOA (Modifier or additive use); USES (Uses) (crosslinking agents, for epoxy resins contg. functional group-terminated siloxanes, for sealants, for semiconductor devices) | | | | |
| IT | Crosslinking agents (for epoxy resins contg. functional group-terminated siloxanes, for sealants, for semiconductor devices) | | | | |
| IT | Siloxanes and Silicones, uses RL: USES (Uses) (epoxy, sealing compns., contg. silica fillers, with solder heat resistance, for semiconductor device) | | | | |
| IT | Siloxanes and Silicones, compounds RL: USES (Uses) (epoxy-terminated, reaction products with epoxy resins , for sealants, for semiconductor devices) | | | | |
| IT | Epoxy resins , uses RL: USES (Uses) (siloxane-, sealing compns., contg. silica fillers, with solder heat resistance, for semiconductor device) | | | | |

IT 7727-33-5

RL: MOA (Modifier or additive use); USES (Uses)
(crosslinking agents, for **epoxy resins** contg.
functional group-terminated siloxanes, for sealants, for semiconductor
devices)

IT 25639-41-2

RL: MOA (Modifier or additive use); USES (Uses)
(crosslinking agents, for **epoxy resins** contg.
functional group-terminated siloxanes, for sealants, for semiconductor
devices)

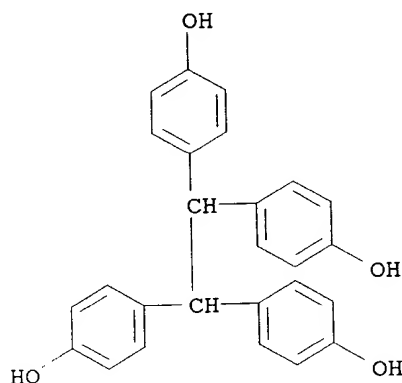
IT 60676-86-0, Fused silica

RL: USES (Uses)
(powd., fillers, for **epoxy resin** sealing compns.
contg. functional group-contg. siloxanes, for semiconductor devices)

IT 89118-70-7DP, YX 4000, reaction products with siloxanes

RL: PREP (Preparation)
(prepn. of, sealants, with solder heat resistance, for semiconductor
devices)

RN 7727-33-5 REGISTRY
 CN Phenol, 4,4',4'',4'''-(1,2-ethanediylidene)tetrakis- (9CI) (CA INDEX NAME)
 OTHER CA INDEX NAMES:
 CN Phenol, 4,4',4'',4'''-ethanediylidenetetra- (6CI)
 OTHER NAMES:
 CN 1,1,2,2-Tetrakis(4-hydroxyphenyl)ethane
 CN 1,1,2,2-Tetrakis(p-hydroxyphenyl)ethane
 CN TEP-DF
 MF C26 H22 O4
 CI COM
 LC STN Files: BEILSTEIN*, BIOSIS, CA, CAOLD, CAPLUS, CASREACT, CHEMCATS, CHEMLIST, IFICDB, IFIUDB, TOXLIT, USPATFULL
 (*File contains numerically searchable property data)
 Other Sources: EINECS**, NDSL**, TSCA**
 (**Enter CHEMLIST File for up-to-date regulatory information)



59 REFERENCES IN FILE CA (1967 TO DATE)
 8 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
 59 REFERENCES IN FILE CAPLUS (1967 TO DATE)
 1 REFERENCES IN FILE CAOLD (PRIOR TO 1967)